



To: Technology Center: ISSUE FEES
Facsimile Number: (571)273-2885

Total Pages Sent: 2

From: Jacqueline J. Garner
Texas Instruments Incorporated
Facsimile: 972-917-4418
Phone: 214 532-9348

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Richard T. Goldberg Docket No.: TI-25588
Serial No.: 09/085,298 Art Unit: 2822
Filed: May 27, 1998 Examiner: Khanh B. Duong
Customer No.: 23494 Conf. No.: 6700
For: Method for Thermal Nitridation and Oxidation of Semiconductor Surface

CERTIFICATION OF FACSIMILE TRANSMISSION

I hereby certify that the following papers are being transmitted by facsimile to the U.S. Patent and Trademark Office 571-273-2885 on the date shown below:

Marianna Smith
Marianna Smith

10-13-05
Date

FACSIMILE COVER SHEET

<input checked="" type="checkbox"/> FACSIMILE COVER SHEET		<input type="checkbox"/> AMENDMENT <input checked="" type="checkbox"/> (# Pages)
<input type="checkbox"/> NEW APPLICATION		<input type="checkbox"/> EOT <input checked="" type="checkbox"/> (# Pages)
<input type="checkbox"/> DECLARATION (# Pages)		<input type="checkbox"/> NOTICE OF APPEAL (# Pages)
<input type="checkbox"/> ASSIGNMENT (# Pages)		<input type="checkbox"/> APPEAL <input checked="" type="checkbox"/> (# Pages)
<input type="checkbox"/> FORMAL DRAWINGS		<input checked="" type="checkbox"/> ISSUE FEE (1 Page)
<input type="checkbox"/> INFORMAL DRAWINGS		<input type="checkbox"/> REPLY BRIEF (IN TRIPPLICATE) (# Pages)
<input type="checkbox"/> CONTINUATION APPN (# Pages)		
<input type="checkbox"/> DIVISIONAL APPN		
NAME OF INVENTOR(S):		
Richard T. Goldberg		
TITLE OF INVENTION:		
Method for Thermal Nitridation and Oxidation of Semiconductor Surface		
TI FILE NO.:	DEPOSIT ACCT. NO.:	
TI-25588	20-0668	
FAXED:	10/13/2005	
DUE:	12/02/2005	
ATTY/SÉC'Y:	JJG/ms	

This facsimile is intended only for the use of the address named and contains legally privileged and/or confidential information. If you are not the intended recipient of this telecopy, you are hereby notified that any dissemination, distribution, copying or use of this communication is strictly prohibited. Applicable privileges are not waived by virtue of the document having been transmitted by Facsimile. Any misdirected facsimiles should be returned to the sender by mail at the address indicated on this cover sheet.

Texas Instruments Incorporated
PO Box 655474, M/S 3999
Dallas, TX 75265